

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

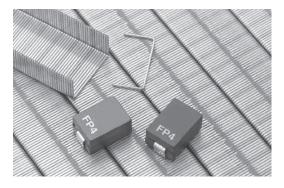






FP4

High current power inductors



Product description

- · High current carrying capacity
- Inductance range from 0.090uH to 0.200uH
- Current range 30 to 72 Amps
- 10.2 x 6.8mm footprint surface mount package in a 5.0mm height
- · Ferrite core material
- · Halogen free, lead free, RoHS compliant

Applications

- Servers
- Multi-phase and Vcore regulators
- Voltage Regulator Modules (VRMs)
 - Server and desktop
 - Central processing unit (CPU)
 - Graphics processing unit (GPU)
 - Application specific integrated circuit (ASIC)
 - · High power density
- · Battery power systems
- · Graphics cards

Environmental data

- Storage temperature range (component): -40°C to +155°C
- Operating temperature range: -45°C to +155°C (Ambient plus self temperature rise)
- Solder reflow temperature: J-STD-020D compliant









Product specifications

Part number ⁵	OCL¹ (μH) ±15%	I _{rms} ² (amps)	l _{sat} ³ (amps)	DCR (Ω) typical @ 20°C	DCR (Ω) maximum @ 20°C	Volt-µsec⁴ (V-usec)
FP4-100-R	0.100	40	64	0.00038	0.00065	1.33
FP4-120-R	0.120	40	54	0.00038	0.00065	1.33
FP4-150-R	0.150	40	42	0.00038	0.00065	1.33
FP4-200-R	0.200	40	30	0.00038	0.00065	1.33

- 1. Open Circuit Inductance (OCL) Test parameters: 1MHz, 0.100Vrms, 0.0Adc @20°C.
- Irms: DC current for an approximate ΔT of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, airflow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 155°C.
- 3. Isat: Peak current for approximately 30% rolloff @ +20°C.

- 4. Applied Volt-Time product (V-µs) across the inductor. This value represents the applied V-µs at 500kHz necessary to generate a core loss equal to 10% of the total losses for 40°C temperature rise.
- 5. Part Number Definition: FP4-xxx-R

FP4 = Product code and size

xxx= Inductance value in uH, R= decimal point

-R suffix = RoHS compliant

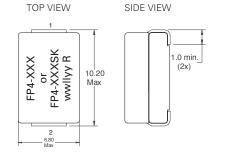
Part number⁵	OCL¹ (μH) ±15%	I _{rms} ² (amps)	l _{sat} ³ (amps)	DCR (mΩ) @25°C	Volt-µsec⁴ (V-usec)	
FP4-090SK-R	0.090	33	72	0.423-0.517	1.33	

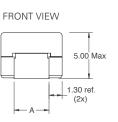
- 1. Open Circuit Inductance (OCL) Test parameters: 100kHz, 1.0Vrms, 0.0Adc @25°C.
- Irms: DC current for an approximate ΔT of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, airflow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 155°C.
- 3. Isat: Peak current for approximately 20% rolloff @ +25°C.

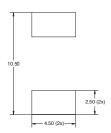
- Applied Volt-Time product (V-µs) across the inductor. This value represents the applied V-µs at 500kHz necessary to generate a core loss equal to 10% of the total losses for 40°C temperature rise.
- Part Number Definition: FP4-xxxSK-R
 FP4, SK = Product code and size
 xxx= Inductance value in uH, R= decimal point
 -R suffix = RoHS compliant

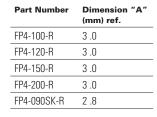
RECOMMENDED PAD LAYOUT

Dimensions-mm









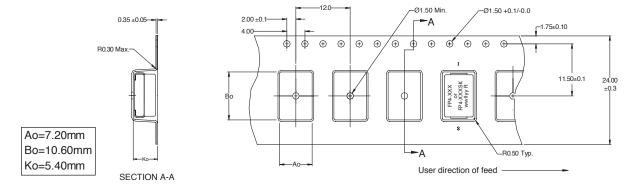


Part marking:

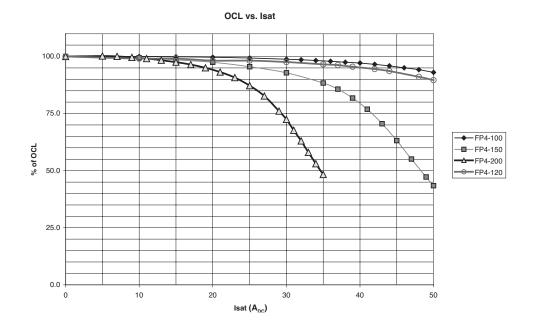
FP4-xxx (FP4=Product code and size),(xxx=inductance value in uH, R=decimal point)
FP4-xxxSK (FP4, SK=Product code and size),(xxx=inductance value in uH, R=decimal point)
wwllyy = date code, R = revision level
Tolerances are ±0.15 millimeters unless stated otherwise
PCB tolerances are ±0.2 millimeters unless stated otherwise
Do not route traces or vias underneath the inductor

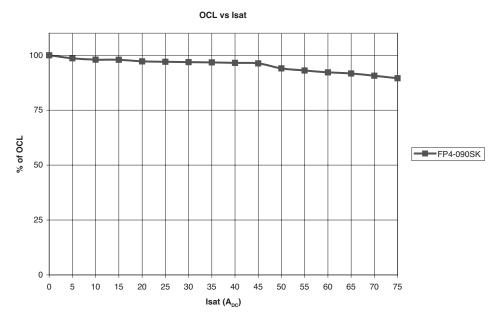
Packaging information (mm)

Supplied in tape and reel packaging, 900 parts per 13" diameter reel.

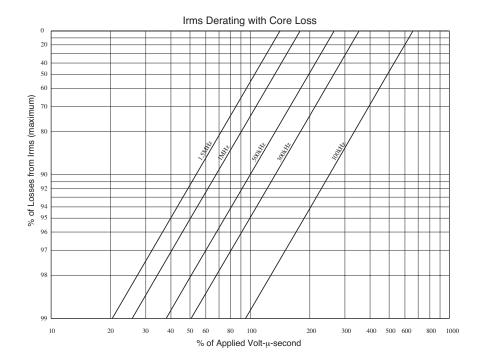


Inductance characteristics

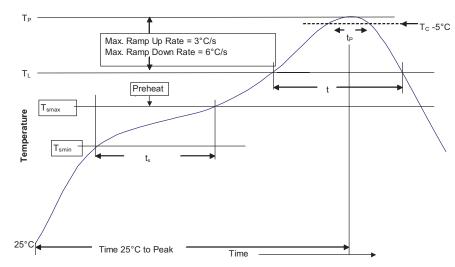




Core loss



Solder reflow profile



-_{Tc-5°C} Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak • Temperature min. (T _{smin})	100°C	150°C	
• Temperature max. (T _{smax})	150°C	200°C	
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds	
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL) Time at liquidous (tL)	183°C 60-150 Seconds	217°C 60-150 Seconds	
Peak package body temperature (Tp)*	Table 1	Table 2	
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**	
Average ramp-down rate (T _p to T _{smax})	6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.	

 $^{^{*}}$ Tolerance for peak profile temperature (T $_{\rm p}$) is defined as a supplier minimum and a user maximum.

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Eaton Electronics Division 1000 Eaton Boulevard Cleveland, OH 44122 United States www.eaton.com/elx

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^{**} Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.